

**Amendment and Response**

Applicant: Edward Fuergut et al.

Serial No.: 10/561,819

Filed: December 22, 2005

Docket No.: I431.139.101/FIN474PCT/US

Title: SENSOR COMPONENT AND PANEL USED FOR THE PRODUCTION THEREOF

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**REMARKS**

The following remarks are made in response to the Non-Final Office Action mailed May 28, 2008. Claims 20-31 have been withdrawn from consideration in response to an earlier restriction requirement. With this Response, claims 14 and 32 have been amended. Claims 14-19, 32 and 33 remain pending in the application and are presented for reconsideration and allowance.

**Claim Rejections under 35 U.S.C. § 102**

Claims 14, 18-19 and 32 were rejected under 35 U.S.C. 102(b) as allegedly being anticipated by Yamamoto et al. (US Pub. 2003/0094675).

Independent claims 14 and 32 have been amended to more clearly recite the claimed component. For example, claims 14 and 32 each recite “a plastic plate, in which the sensor chip is embedded by its rear side and its edge sides, the active top side of the sensor chip and top sides of the contact areas, together with a top side of the plastic plate having a planar overall top side.”

Claim 14 further recites “a rewiring structure with a rewiring layer having flat rewiring lines from the contact areas to external contact areas of the sensor components, the rewiring structure being arranged on the planar overall top side.”

Claim 32 is presented in “means-plus-function” language as provided by 35 USC 112, sixth paragraph. As such, the claim should be interpreted in view of the structure disclosed that corresponds to the “means” associated with the recited function. *See, In re Donaldson*, 16 F.3d 1189, 29 USPQ2d 1845 (Fed. Cir. 1994). Thus, the means for connecting the contact areas to the external contact areas of the sensor components includes a rewiring structure with a rewiring layer having flat rewiring lines arranged on the planar overall top side as disclosed in the drawings and written description of the present application.

Yamamoto fails to disclose each element of claims 14 and 32. For example, Yamamoto fails to disclose the active top side of the sensor chip and top sides of the contact areas, together with a top side of the plastic plate have a planar overall top side. Instead, Yamamoto shows in Figure 1(B) and 1(C) that the semiconductor chip 1 is embedded in the package 3 which has

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guide projections 4 and spring projections 5 arranged vertically higher than the semiconductor chip 1. Moreover, the wires 8 electrically connecting the electrodes 1b of the semiconductor chip 1 and the leads 2 also extend vertically higher than the topside of the semiconductor chip 1.

Moreover, the semiconductor device disclosed in Yamamoto contains guide projections 4 and spring projections 5 extending vertically higher than the top side of the semiconductor chip 1 in order to align semiconductor chip 1 for die bonding on the die pad section. Arranging the guide projection 4 and spring projections 5 in such a way as to form a planar overall top side together with the active top side of the semiconductor chip 1 would lead to less alignment of the semiconductor chip 1 and thus the risk of failure of the semiconductor device.

Further, the wires 8 would still be needed to electrically connect the electrodes 1b of the semiconductor chip 1 and the leads 2. Thus, one of ordinary skill in the art would have no motivation to use flat rewiring lines electrically connecting the contact areas of the semiconductor chip 1 to external contact areas of the semiconductor device.

Accordingly, Applicants respectfully submit that claims 14 and 32, as well as 18 and 19 dependent on claim 14, are in condition for allowance.

**Claim Rejections under 35 U.S.C. § 103**

Claims 15-17 and 33 were rejected under 35 U.S.C. 103(a) as allegedly being unpatentable over Yamamoto et al. (US Pub. 2003/0094675) in view of Fillion et al. (US 5,353,498).

Claims 15-17 depend from claim 14, and claim 32 depends from claim 32. As such, these claims are allowable for at least the same reasons set forth herein with respect to the rejections under 35 USC 102.

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**CONCLUSION**

In view of the above, Applicant respectfully submits that the pending claims are in form for allowance and are not taught or suggested by the cited references. Therefore, reconsideration and withdrawal of the rejections and allowance of the claims are respectfully requested.

No fees are required under 37 C.F.R. 1.16(h)(i). However, if such fees are required, the Patent Office is hereby authorized to charge Deposit Account No. 50-0471.

The Examiner is invited to contact the Applicant's representative at the below-listed telephone numbers to facilitate prosecution of this application.

Any inquiry regarding this Amendment and Response should be directed to Mark L. Gleason at Telephone No. (612) 767-2503, Facsimile No. (612) 573-2005. In addition, all correspondence should continue to be directed to the following address:

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Respectfully submitted,

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